

# GSM02P15JZF

## 150V P-Channel MOSFETs Preliminary Datasheet

### General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

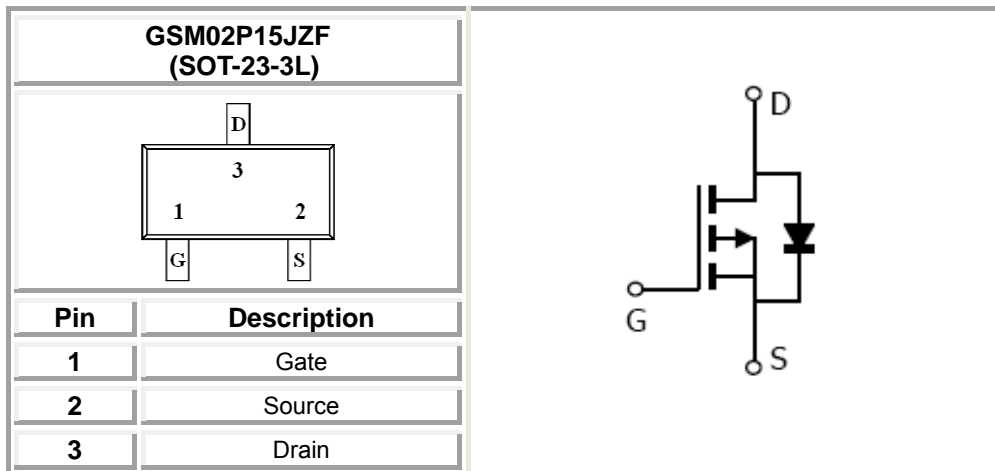
### Features

- -150V/-1A,  $R_{DS(ON)}=750m\Omega@V_{GS}=-1V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

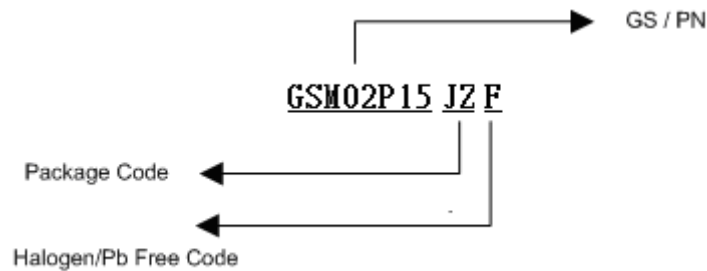
### Applications

- Networking
- Load Switch
- LED applications

### Packages & Pin Assignments

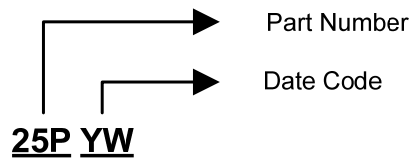


### Ordering Information



Part Number	Package	Quantity Reel
GSM02P15JZF	SOT-23-3L	3000 PCS

## Marking Information



## Absolute Maximum Ratings

( $T_A=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Typical	Unit
$V_{DS}$	Drain-Source Voltage	-150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current- Continuous ( $T_A=25^\circ\text{C}$ )	-1	A
	Drain Current- Continuous ( $T_A=100^\circ\text{C}$ )	-0.63	A
$I_{DM}$	Drain Current- Pulsed	-4	A
$P_D$	Power Dissipation ( $T_A=25^\circ\text{C}$ )	1.56	W
	Power Dissipation -Derate above $25^\circ\text{C}$	0.012	W/ $^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-50 to 150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-50 to 150	$^\circ\text{C}$

## Thermal Characteristics

Symbol	Parameter	Typ.	Max	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to ambient	---	80	$^\circ\text{C}/\text{W}$

## Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	-150	---	---	V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-2	-3	-4	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V	---	---	±100	nA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-150V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-120V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	-10	
R <sub>DS(on)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =-1A	---	650	800	mΩ
		V <sub>GS</sub> =6V, I <sub>D</sub> =-0.5A	---	700	650	
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =-1A, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	-1	V
<b>Dynamic</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-25V, V <sub>GS</sub> =0V, F=1MHz	---	430	700	pF
C <sub>oss</sub>	Output Capacitance		---	38	60	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	28	56	
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-75V, V <sub>GS</sub> =10V, I <sub>D</sub> =-1A	---	4.4	8	nC
Q <sub>gs</sub>	Gate-Source Charge		---	0.7	2	
Q <sub>gd</sub>	Gate-Drain Charge		---	1.5	3	
t <sub>d(on)</sub>	Turn-On Time	V <sub>DD</sub> =-75V, V <sub>GS</sub> =-10V, R <sub>G</sub> =10Ω, I <sub>D</sub> =-1A,	---	12.5	20	ns
t <sub>r</sub>			---	8.9	18	
t <sub>d(off)</sub>	Turn-Off Time		---	17.3	36	
t <sub>f</sub>			---	11.5	24	

## Typical Performance Characteristics

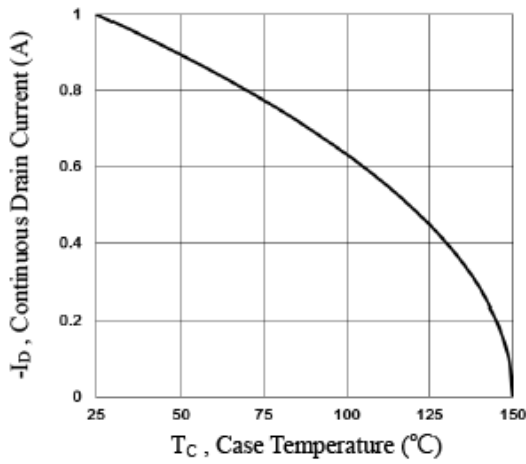


Fig.1 Continuous Drain Current vs.  $T_c$

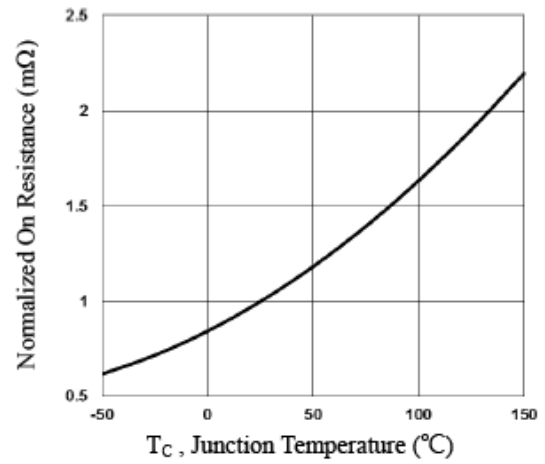


Fig.2 Continuous Drain Current vs.  $T_c$

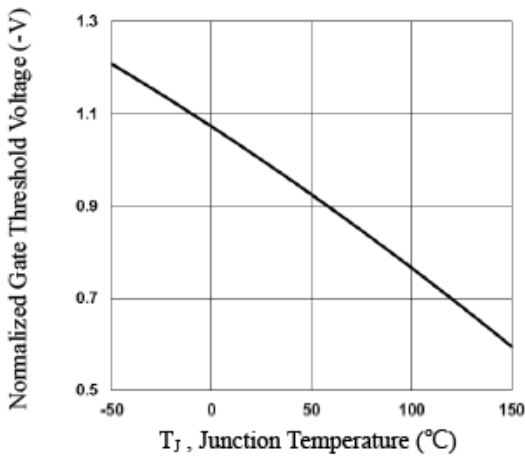


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

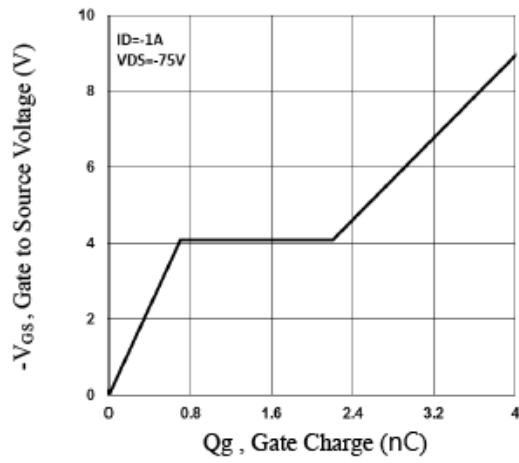


Fig.4 Gate Charge Waveform

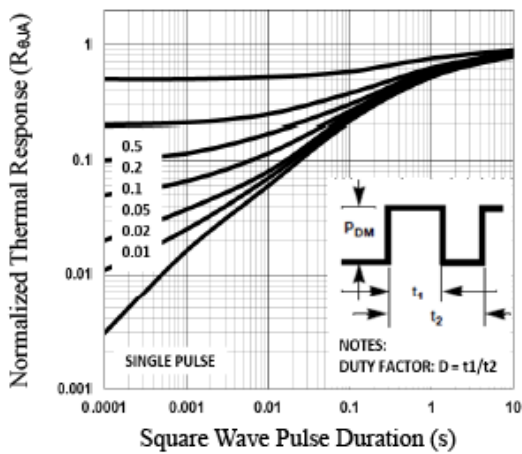


Fig.5 Normalized Transient Impedance

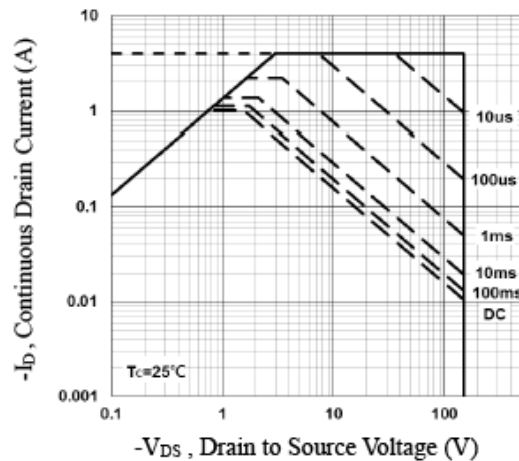


Fig.6 Maximum Safe Operation Area

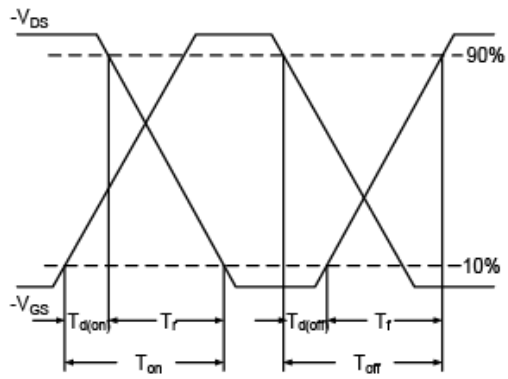


Fig.7 Switching Time Waveform

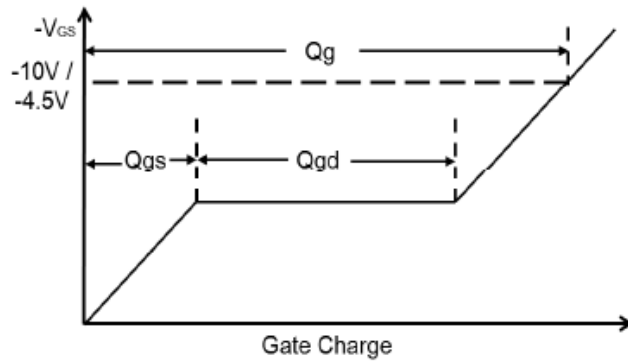
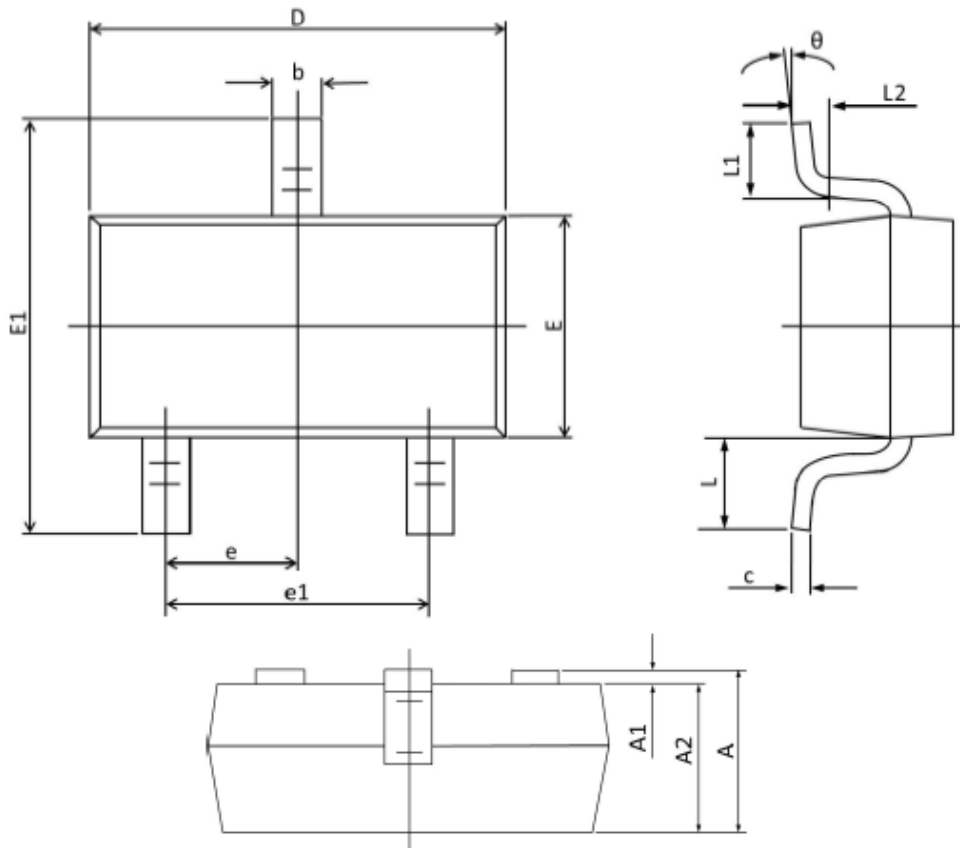


Fig.8 Gate Charge Waveform

## Package Dimension

### SOT23-3S PACKAGE INFORMATION







Dimensions				
SYMBOL	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.008
D	2.800	3.000	0.110	0.006
E	1.200	1.400	0.047	0.118
E1	2.250	2.550	0.089	0.055
e	0.950 (TYP)		0.037 (TYP)	
e1	1.800	2.000	0.071	0.079
L	0.55(REF)		0.028 (REF)	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°



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